Methods, FMF, Fiederle

Technology Lab Clean Room Facility	Ur	Model: nit and Room: Responsible: Further information:	 FMF, Physics Hall
Short Description:			Picture of the Equipment
Full equipped clean room facility for processing Available Experiments/Techniques: Mask aligner Surface profiler Optical microscope Plasma Ion Etcher Electron Gun Sputtering facility Flip-chip bonder Reflow furnace		Sputter Coater: v. Ardenne GmbH Flip-Chip-Bonder Finetec	Dry Etcher 4TEC Wire-Bonder Shinkawa Wire-Bonder Wire-
Special Equipment: Processing of samples and devices for deposition of metals and passivation			
Processing of micrometer structures down to 1 µm precision			
Measurements on the equipment are currently done by:		☐Students ☐Students after Introduction ☐Students after extensive training ☐Trained scientific service personal	
Recent Publications, where this instrument was important (optional): Give citation		•	
Typical problems that may be solve with this instrument:	ed		ssing of device structures opment of metallization and passivation